

Amendments to the Abstract:

Please replace the paragraph beginning at page 6, line 2, with the following rewritten paragraph:

-- An integrated circuit package ~~having central leads~~ comprises a substrate 5 ~~has~~having an upper surface, a lower surface, and a long slot penetrating ~~from~~the upper surface to the lower surface. The lower surface is ~~forming~~formed with a wiring regions arranged at ~~the two sides~~one side of the long slot, and the wiring regions ~~are~~is ~~forming~~formed with a plurality of ~~connected~~connection points. A glue layer is coated on the upper surface of the substrate and is arranged at the 10 periphery of the long slot. The integrated circuit has a first surface ~~forming~~formed with a plurality of bonding pads ~~and~~which is adhered to the glue layer. The wires, each of which is arranged within the long slot of the substrate, ~~and~~ is electrically connected the bonding pads of the integrated circuit to the ~~connected~~connection points of the substrate, ~~and~~ The first compound layer is filled within 15 the long slot of the substrate ~~for protecting to protect~~ the each wires. --